



Material Content Data Sheet



Sales Product Name		TLE4953C		Issued		27. September 2017		
MA#		MA000862106						
Package		PG-SSO-2-4		Weight*		168.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.522	1.49	1.49	14927	14927
leadframe	non noble metal	chromium	7440-47-3	0.288	0.17		1704	
	non noble metal	titanium	7440-32-6	0.288	0.17		1704	
	non noble metal	nickel	7440-02-0	0.384	0.23		2272	
	non noble metal	tin	7440-31-5	0.576	0.34		3409	
	non noble metal	copper	7440-50-8	94.449	55.91	56.82	559020	568109
wire	noble metal	gold	7440-57-5	0.039	0.02	0.02	233	233
encapsulation	organic material	carbon black	1333-86-4	0.450	0.27		2661	
	plastics	brominated resin	-	0.562	0.33		3326	
	inorganic material	antimonytrioxide	1309-64-4	1.124	0.67		6652	
	plastics	epoxy resin	-	10.228	6.05		60537	
	inorganic material	silicondioxide	60676-86-0	43.834	25.94	33.26	259443	332619
leadfinish	non noble metal	tin	7440-31-5	6.247	3.70	3.70	36974	36974
plating	noble metal	silver	7440-22-4	0.986	0.58	0.58	5834	5834
glue	plastics	epoxy resin	-	0.156	0.09		922	
	noble metal	silver	7440-22-4	0.623	0.37	0.46	3686	4608
smd	inorganic material	leadoxide	1317-36-8	0.001	0.00		7	
	inorganic material	titandioxide	13463-67-7	0.148	0.09		876	
	inorganic material	leadtitanate	12060-00-3	0.031	0.02		183	
	plastics	epoxy resin	-	0.002	0.00		12	
	inorganic material	bismuth trioxide	1304-76-3	0.255	0.15		1509	
	noble metal	palladium	7440-05-3	0.474	0.28		2806	
	noble metal	silver	7440-22-4	1.499	0.89		8873	
	inorganic material	bariumtitanate	12047-27-7	3.790	2.24	3.67	22430	36696
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7 (c)-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.

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